

501.36931X00
Expedited Procedure Requested
Amendment Under 37 CFR 1.116
Group 2813

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): IWASAKI, et al.

Serial No.: 09/255,856

Filed: February 23, 1999

For: SEMICONDUCTOR DEVICE WITH LAYERED INTERCONNECT
STRUCTURE

Group: 2813

Examiner: S. Smoot

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents
BOX AF
Washington, D.C. 20231

May 17, 2001

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TECHNOLOGY CENTER 2800

5-18-01

Sir:

In response to the Office Action mailed December 11, 2000, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 8, 21 and 26 without prejudice or disclaimer, and amend the claims remaining in the application as follows:

- Do Not Enter
S.W.B.
5-24-01
J.W.
-
1. (Amended) A semiconductor device with a multilayered structure comprising a copper film interconnect formed on one primary surface of a semiconductor substrate, and a neighboring film formed in contact with said copper film interconnect, wherein said neighboring film is formed of a